

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT:	C. Huang	CONF. NO.:	5161
U.S. SERIAL NO.:	10/787,269	EXAMINER:	P. Cao
FILED:	February 25, 2004	GROUP:	2814
FOR:	SEMICONDUCTOR PACKAGE WITH HEAT DISSIPATING STRUCTURE		

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

AMENDMENT

Applicant is in receipt of the Office Action dated June 19, 2007 of the above-referenced application. Please amend the application as follows:

Amendments to the claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 7 of this paper.